



1 Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"] FR4/G10 or equivalent high temp material. 17 $\mu$ m [1/2 oz.] Cu clad. SnPb plating.

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 $\mu$ m [10 $\mu$ "] Au over 1.27 $\mu$ m [50 $\mu$ "] Ni (min.).

3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25 $\mu$ m [10 $\mu$ "] Au over 1.27 $\mu$ m [50 $\mu$ "] Ni (min.). Contact material- BeCu; finish 0.25 $\mu$ m [10 $\mu$ "] Au over 2.54 $\mu$ m [100 $\mu$ "] Ni (min. ).

4 Test points: material- Phosphor Bronze; plating- Sn over 1.27 $\mu$ m [50 $\mu$ "] Ni. Gold flash on contact end.

Description: Carrier Adaptor  
50 position TSOP (type II) ZIF socket to leadless surface mount foot.

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise.

<b>CA-SO50B-L-Z-T-01 Drawing</b>		Status: Released	Scale 2:1	Rev: A
 <p>© 2000 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Drawing: W. Watson		Date: 4/17/00	
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